



NIC COMPONENTS CORP.

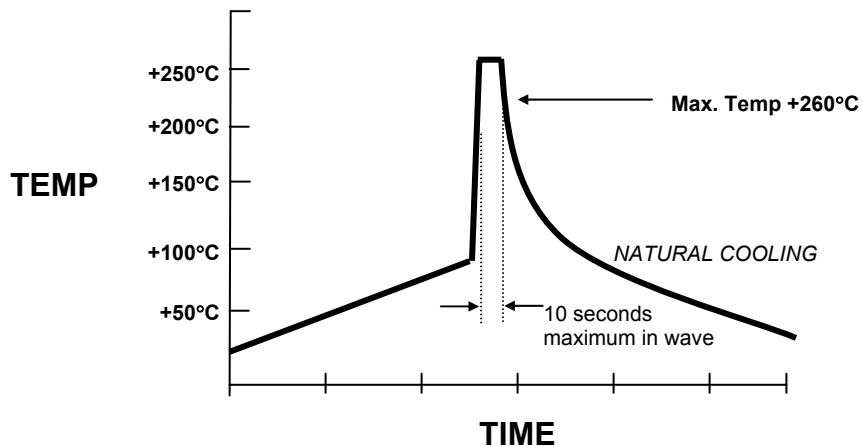
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FLOW / WAVE SOLDERING

PRODUCTS: RADIAL, AXIAL AND SNAP-IN LEADED COMPONENTS

Sn-Pb and Pb-Free Soldering Processes



- The above flow-wave soldering profile applies to all NIC leaded products.
- The temperatures shown above, reflect the conditions seen by the component wire leads
- Exposure of the component body to excessive heat during curing, preheat and soldering operations, may result in damage to the component.
- It is recommended that leaded components be installed after reflow soldering of surface mount components is completed.

If you have any questions, or need any further information, please contact NIC's Technical Support at LINK or e-Mail: tpmg@niccomp.com

ISO 9001 : 2000 REGISTERED